

1. AMENDMENTS TO THE SPECIFICATION.

(i) Replace the paragraph [0001] with the following:

[0001] The present application claims the benefit of priority of US Provisional Patent Application serial No. ~~60/458,099~~ 60/458,200 for Edward Lopatinsky et al. the entire content of which is incorporated herein by reference.

(ii) Replace the paragraph 5th of Section BRIEF DESCRIPTION OF THE DRAWINGS with the following:

Fig. 5 is a perspective view showing the cooler for cooling of electronic components according to the second embodiment ~~without one of the heatsinks exposing the centrifugal blower;~~

(iii) Replace the paragraph 6th of Section BRIEF DESCRIPTION OF THE DRAWINGS with the following:

Fig. 6 is a perspective view showing the [[a]] cooler for cooling of electronic components according to the second embodiment shown in Fig. 5 without one heatsink exposing the centrifugal blower;

(iv) Replace the paragraph [0020] with the following:

[0020] Figures[[.]] 1 - [[4]] 7 show the preferred embodiment embodiments of the present invention.

(v) Replace the paragraph [0021] with the following:

[0021] The cooler 1 for cooling of electronic components (not shown) comprises of at least two heatsinks 2 and 3 thermally connected with each other by heat spreading means 4, and ~~at least one, a double inlet centrifugal blower 5 comprising a casing 6 and 6A with two inlets 7 and 8, and an outlet 9, [[an]] a radial impeller 10 with an axle 11, and an electric drive 12, wherein each of [[said]] the heatsinks 2 and 3 comprises [[an]] inflow openings 13 and 13A, outflow openings 14 and 14A, heat exchanging means 15, and [[a base]] bases 16 and 16A providing thermal contact with [[said]] the heat exchanging means 15. The impeller 10 comprises two sets of radial blades 30 and 30A located from both sides of an impeller disk 27. The double inlet centrifugal blower 5 located between [[said]] heatsinks 2 and 3 thus each of [[said]] the outflow openings 14 and 14A coincide with [[said]] the closest inlet 7 or 8, so cooling air flows through [[said]] the~~

inflow openings 13 and 13A, [[said]] the heat exchanging means [[14]] 15, [[said]] the outflow openings 14 and 14A, and inlets 7 and 8 of [[said]] the blower 5 in a series way.

(vi) Replace the paragraph [0023] with the following:

[0023] The heat spreading means 4 is at least one heat pipe 17 comprising comprises of evaporator 18 and condenser 19 parts, to facilitate [[the]] heat transfer, said parts thermally connected with bases [[15]] 16 and 16A of two different heatsinks 2 and 3.

(vii) Replace the paragraph [0024] with the following:

[0024] According to the second embodiment (Figs. 5 - 7) the [[The]] heat spreading means 4 may further comprise of a high heat conductive plate 20 located from one side of and perpendicular to the bases 16 and 16A. Furthermore, [[said]] the high heat conductive plate 20 thermally connected with [[said]] electronic components (not shown). (Fig. 5 - 7) The heat exchanging means 15 are upstanding pins and/or fins 21 and 21A contacting [[said]] the bases [base] 16 and 16A.

(viii) Replace the paragraph [0025] with the following:

[0025] Both [[the]] upstanding fins 21 and 21A, the [[base]] bases 16 and 16A, and high heat conductive plate 20 are made from high heat conductive material. It is preferably to make the upstanding fins 21 and 21A and the [[base]] bases 16 and 16A as [[a]] single [[whole]] wholes, correspondingly. In this case it is possible to use well-known extrusion technology.

(ix) Replace the paragraph [0027] with the following:

[0027] The electric drive 12 is a flat type motor and comprises the stator [[21]] 22, a magnetized rotor [[22]] 23 and a controller [[23]] (not shown on Figs.). The magnetized rotor [[22]] 23 is combined integrated with the impeller 10.

(x) Replace the paragraph [0028] with the following:

[0028] The stator [[21]] 22 is constructed as printed circuit boards [[24]] 25 that position on the stator plate [[25]] 26 and use with the controller [[23]].

(xi) Replace the paragraph [0029] with the following:

[0029] The controller [[23]] (not shown on Figs.) may be a Full Bridge Drive or a Two Phase-Single Ended Drive, for example of type Fairchild NDSSS58H.

(xii) Replace the paragraph [0030] with the following:

[0030] According to the preferred embodiment the magnetized rotor [[22]] 23 is made of at least one the impeller disk [[26]] 27 rigidly mounted perpendicularly to the axle 11 and connected to the impeller 10. The disk 26 has comprises an outer circumferential array of radial extending unlike and or like magnetized poles [[27]] 28 made like blades 30 and/or 30A located from both sides of the impeller 10. The stator [[21]] 22 comprises of a circumferential array of coils [[28]] 29 on the circuit boards [[24]] 25 placed on stator plate 26, each coil [[28]] 29 is wound about an axis parallel to the axle 11 for generating an axially directed electromagnetic field that interacts with magnetic flux lines of each magnetized pole [[27]] 28.

(xiii) Delete the paragraph [0032] and add the following paragraphs [0033] and [0034]:

[0033] The cooler 1 for cooling of electronic components operates in the following way. When electric power is supplied to the stator 22 (its coils 29) of the electric drive 12, alternate electromagnetic fields are created. These electromagnetic fields interact with a magnetic field created by the magnetized poles 28 made like blades 30 and/or 30A of the impeller 10 which serve as the magnetic rotor 23 of the electric drive 12. As a result the impeller 10 is rotated. Because the blower 5 made as the double inlet centrifugal blower, lower pressure areas are created from the both side of the impeller disk 27. Therefore, cooling air at the ambient temperature starts moving and flows through the inflow openings 13 and 13A of the heat-exchanging means 15 of the heatsinks 2 and 3 simultaneously (the arrows AIR IN illustrated air flow direction are shown on Figs. 1 and 3 - 5). When cooling air flows through the heat-exchanging means 15 the intensive process of heat exchange takes place. After that, heated cooling air flows from both sides in respect to the impeller disk 27 through the outflow openings 14 and 14A, which coincide with the corresponding inlets 7 and 8 of the blower 5. The casing 6 and outlet 9 of the blower 5 form together an outtake path of air to ambient (the arrows AIR OUT illustrated air flow direction are shown on Figs. 1 and 3 - 5).

[0034] According to the first embodiment (Figs. 1 - 4) heat generated by electronic component transfers to the base 16 of the heatsink 3 due its thermal contact and spread to the base 16A of the heatsink 2 by the heat spreading mean 4 made as the heat pipe 17. According to the second embodiment (Figs. 5 - 7) heat generated by electronic component transfers to the high heat conductive plate 20 due its thermal contact and then spread to the bases 16 and 16A of the

heatsinks 3 and 2 correspondingly. For both embodiments heat from the bases 16 and 16A due to the thermal connection transferred to the heat exchanging means 15 of both heatsinks 2 and 3.